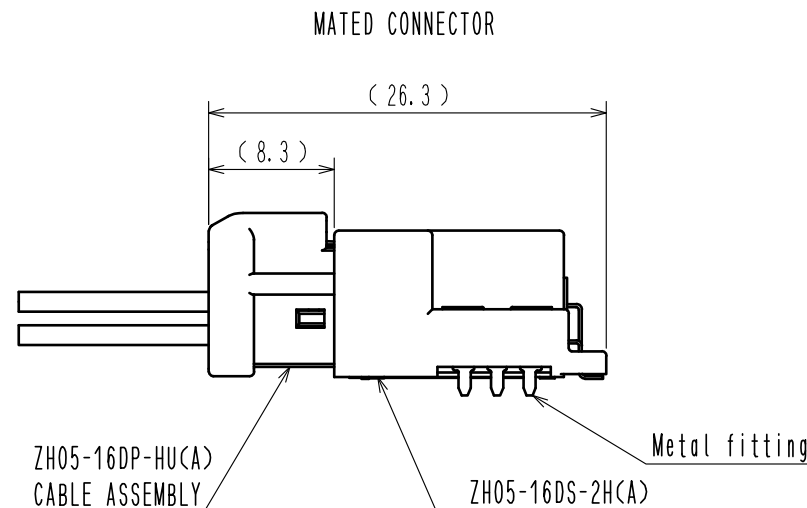
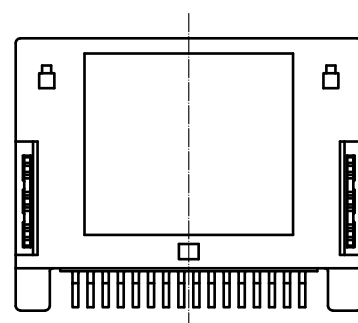
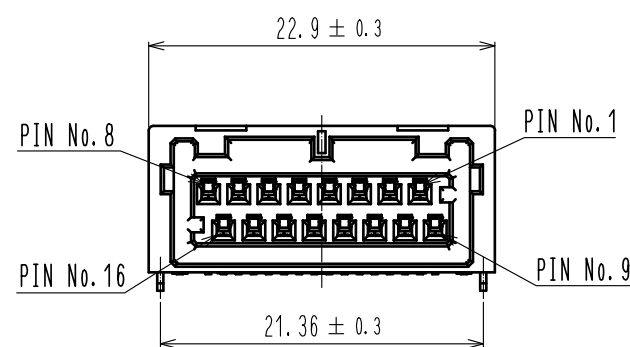
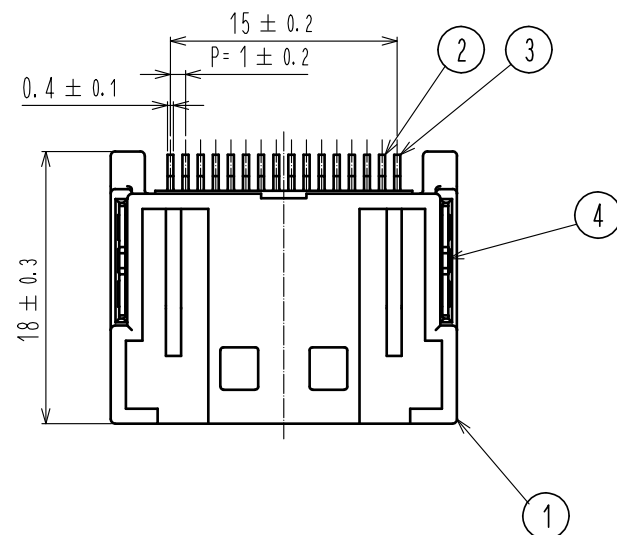
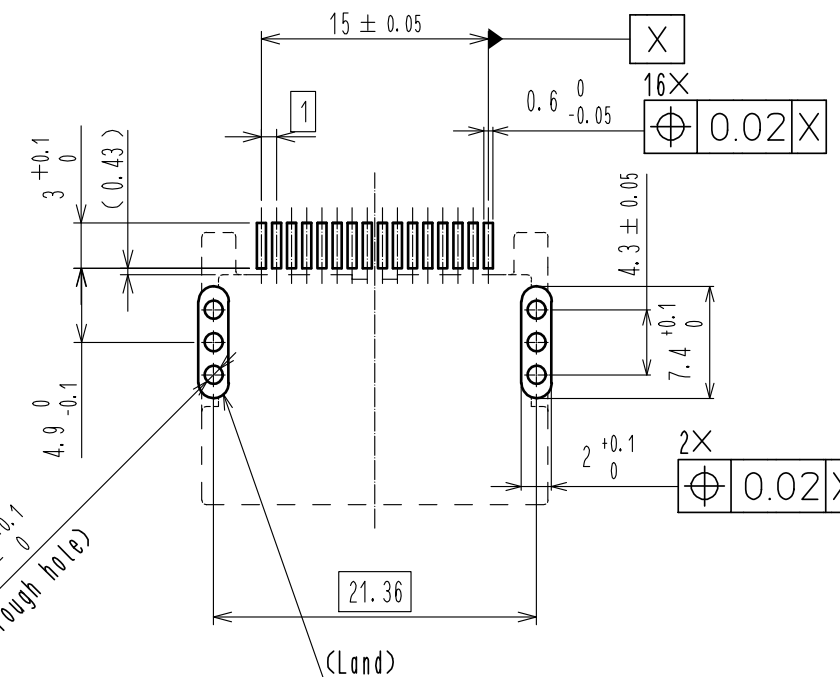


ELV, RoHS COMPLIANT



RECOMMENDED PCB PATTERN (FREE)
(PCB THICKNESS: t=1.6mm. METAL MASK THICKNESS: t=0.1mm)



NOTE 1. RECOMMENDED TEMPERATURE PROFILE FOR REFLOW
(REFER TO RIGHT FIG.)
USED REFLOW SYSTEM

: IR IN THE AIR OR NITROGEN
NO. OF CYCLES : 2 MAX
PEAK : 250°C
OVER 230°C : 20~40s
PREHEAT : 150~180°C
90~120s

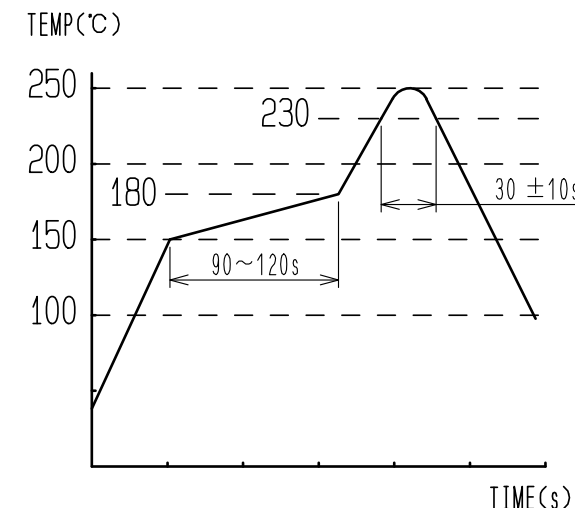
2. TEMPERATURE FOR SOLDERING IRON
: 280~300°C WITHIN 2s

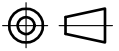
3. CO-PLANARITY SHALL BE 0.1mm MAX.

4. RECOMMENDED PCB THICKNESS IS 1.6mm.

5. RECOMMENDED SOLDER THICKNESS IS 0.10mm.

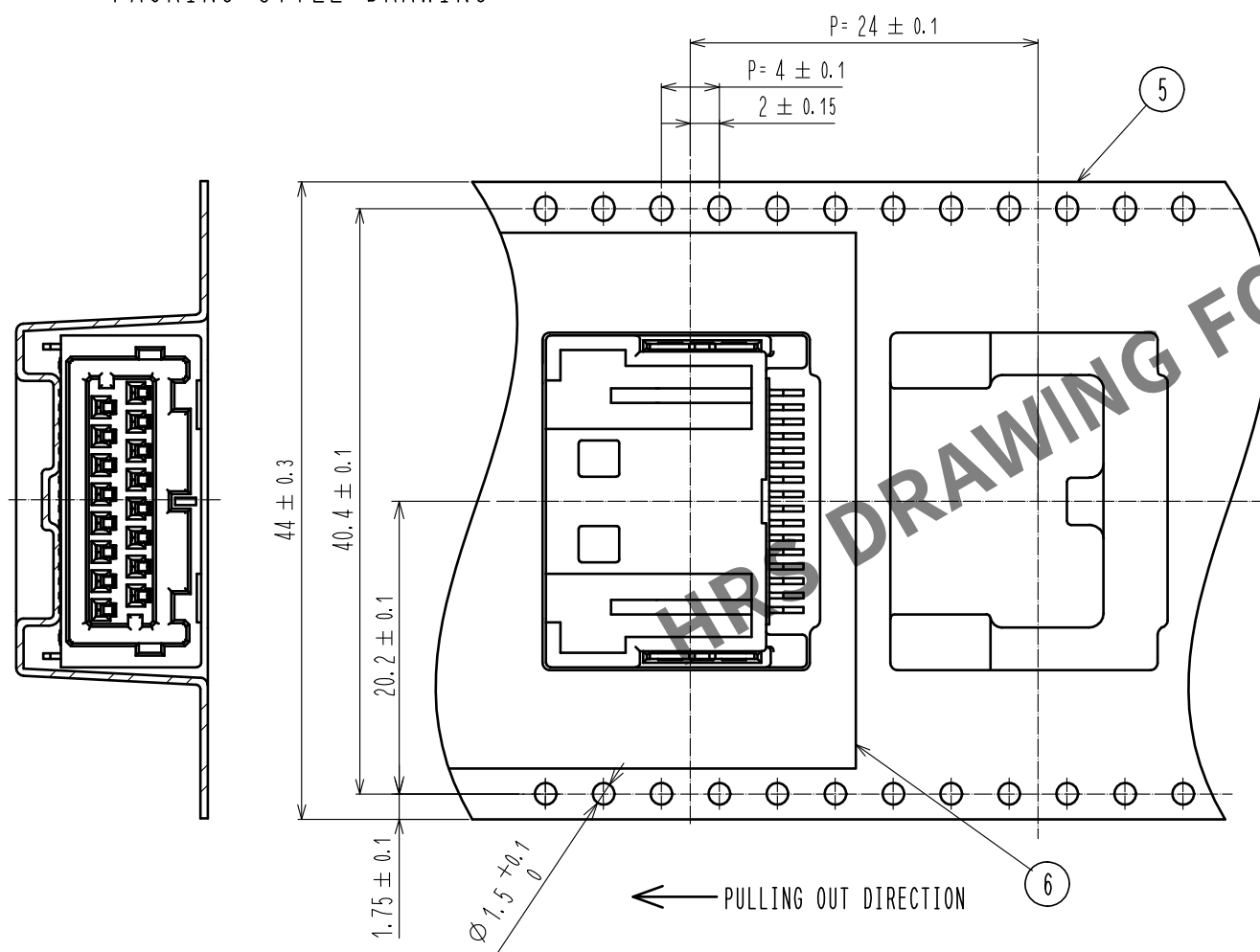
6. ACCORDING TO THE SOLDERING CONDITIONS, THERE ARE EVENTS WHERE SOLDER DOESN' T GET MOLTEN
DUE TO LOW TEMPERATURE OF SOLDERING AREA.
IN SUCH EVENTS, IF REFLOW TEMPERATURE IS RAISED INTENTIONALLY TO GET THE SOLDER MOLTEN,
IT MAY CAUSE EXCESSIVE HEAT OF UP TO 250°C ON THE OUTER (TOP) SURFACE OF CONNECTOR
THAT CAN LEAD TO THE OCCURRENCE OF BLISTER.
PLEASE ENSURE THAT TEMPERATURE OF OUTER (TOP) SURFACE OF CONNECTOR SHALL NOT EXCEED 250°C WHILE SOLDERING.



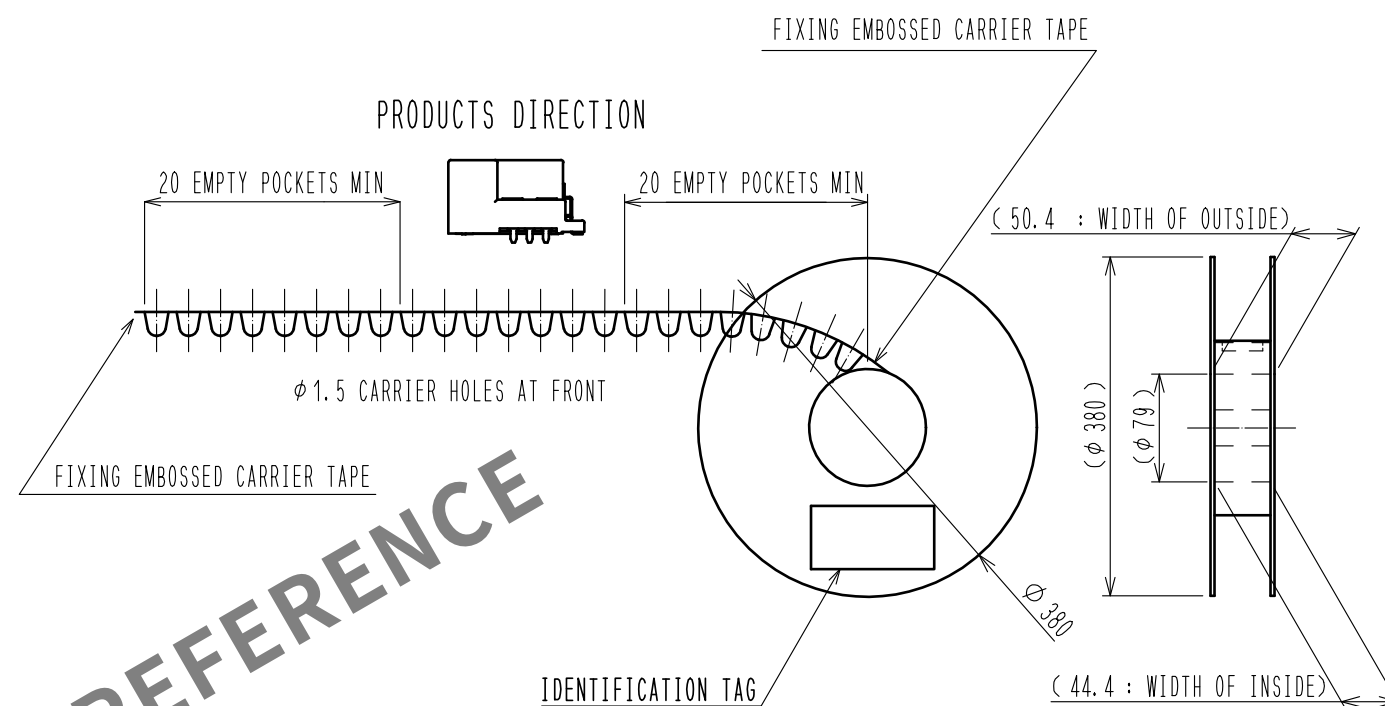
3	COPPER ALLOY	SURFACE : TIN PLATING 1μm min		6	POLYESTER						
2	COPPER ALLOY	SURFACE : TIN PLATING 1μm min		5	POLYSTYRENE						
		UNDER : NICKEL PLATING 1μm min		4	BRASS	SURFACE : TIN PLATING 1μm min					
1	PA	BLACK, UL94V-0						UNDER : NICKEL PLATING 1μm min			
NO.	MATERIAL	FINISH , REMARKS			NO.	MATERIAL	FINISH , REMARKS				
UNITS mm				SCALE 2 : 1		COUNT 1	DESCRIPTION OF REVISIONS DIS-T-00011473		DESIGNED AN. SAIKI	CHECKED KH. MARUNO	DATE 20211008
		APPROVED : OM. MIYAMOTO		20191220		DRAWING NO. EDC-386853-00-00					
		CHECKED : OM. MIYAMOTO		20191220		PART NO. ZH05-16DS-2H(A)					
		DESIGNED : KH. MARUNO		20191220		CODE NO. CL0756-2101-0-00					
		DRAWN : KH. MARUNO		20191220		 					

PACKING STYLE

PACKING STYLE DRAWING



REEL DIMENSION (FREE)



250 PCS/REEL
5 REELS/CARTON

CARDBOARD DIMENSION (FREE)

W=(405) (mm)
D=(405) (mm)
H=(350) (mm)

